IN THE SPECIFICATION

**At page 7, please make the following amendments to paragraphs 0020:**

**Figure 3** depicts a layer 310 disposed on underlying layer 205 after a zeolite – sol colloid, such as zeolite – sol colloid 115 as shown in **Figure 1**, has been deposited on underlying layer 205 through deposition process 305. The zeolite – sol colloid may be deposited on underlying layer 205 in any variety of known methods. For example, the zeolite – sol colloid may be deposited by dip-coating underlying layer 205 in the zeolite – sol colloid. As another example, the zeolite – sol colloid may be deposited by spin-coating the zeolite – sol colloid on underlying layer 205. It is readily apparent that these well-known methods, as well as other well-known methods, of depositing dielectric material may be used to deposit the zeolite - sol colloid on underlying layer 205.

**At page 9, please make the following amendments to paragraphs 0024:**

Furthermore, as shown in Figure 5, approximately any remaining liquid in the wet gel (previously formed from a zeolite – sol colloid) may be extracted to form aerogel – zeolite composite 510 through extraction step 605. By using different extraction conditions (vacuum, temperatures, various extraction rate), the resulting aerogel – zeolite composite 510 is variable to obtain different mechanical properties and k values. The extraction of the remaining liquid may be done by the same methods aforementioned in reference to extraction step 405 shown in Figure 4.

**At page 10, please make the following amendments to paragraphs 0026:**

Referring to Figure 7 and Figure 8 further damascene processing may be done on the wet gel – zeolite or aerogel – zeolite composite film. To simply further damascene processing, Figures 7 and

8 depict an aerogel – zeolite composite ILD ~~710~~ 715. However, it is readily apparent that any amount of liquid may be removed from a liquid sol – zeolite colloid to form either a wet gel, an aerogel, or anywhere in between a wet gel and aerogel composite with zeolite depending on the properties desired. In Figure 7, a via opening 705 and a trench 710 is etched in aerogel – zeolite composite ILD 715. In Figure 8, a barrier layer 805 is deposited on the surfaces of aerogel – zeolite composite ILD 715. Then conductive material 810 is formed in via opening 705 and trench 710. It is apparent that other well-known steps, such as chemical mechanical polish (CMP) and materials, such as copper, tantalum, etc., in the damascene process have been left out so as not to obscure the discussion of the sol gel zeolite composite material.